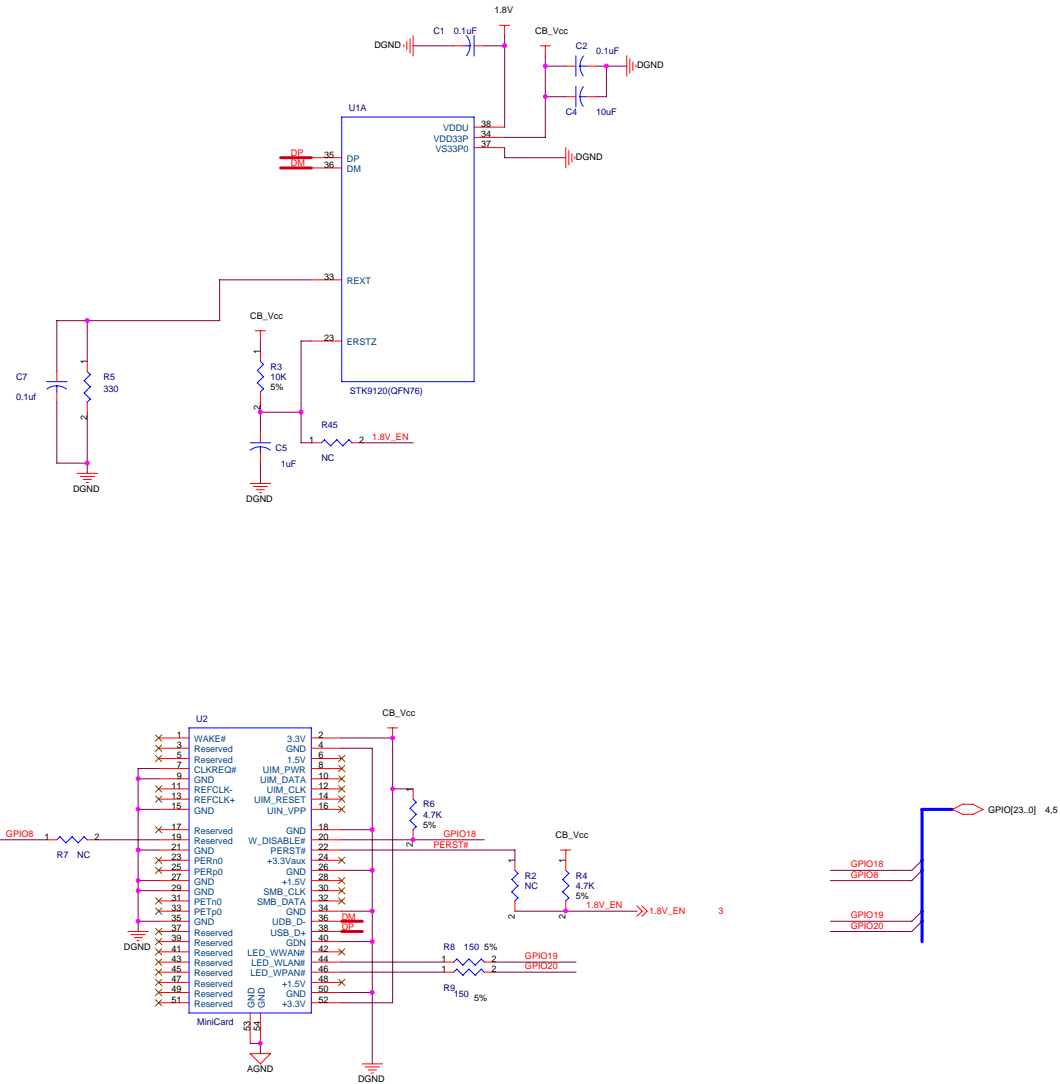
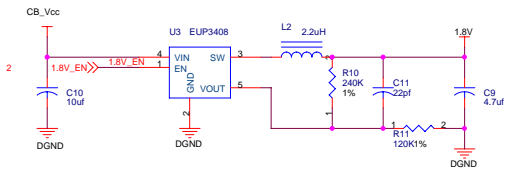


Refer to Layout Reference for placement info



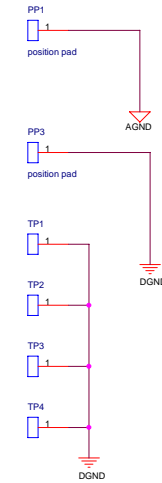
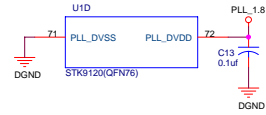
Title		
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Thick trace to handle 1A @ 3.3V



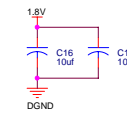
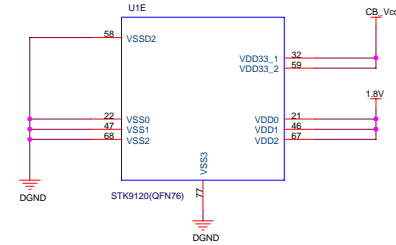
PUT A LOT OF COPPER AROUND
TO ABSORB HEAT

Thick trace to handle 10mA @ 2.0V
Run as a trace not plane

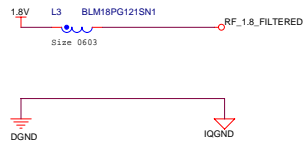


These need to be placed close to power pins
These ones should be on top

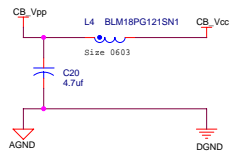
Chip may draw up to 1.5A @ 2.0V



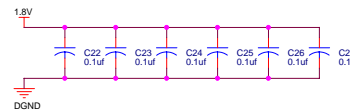
The traces should run through the Caps
Thick trace to handle .3A @ 2.0V



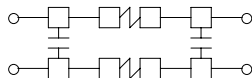
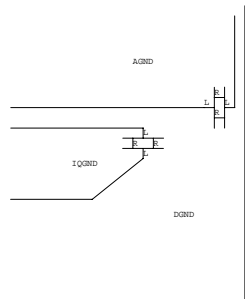
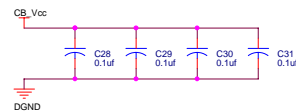
Place between Digital and RF power sections on the board
Thick traces to handle 1A at 3.3V
The traces should run through the Caps



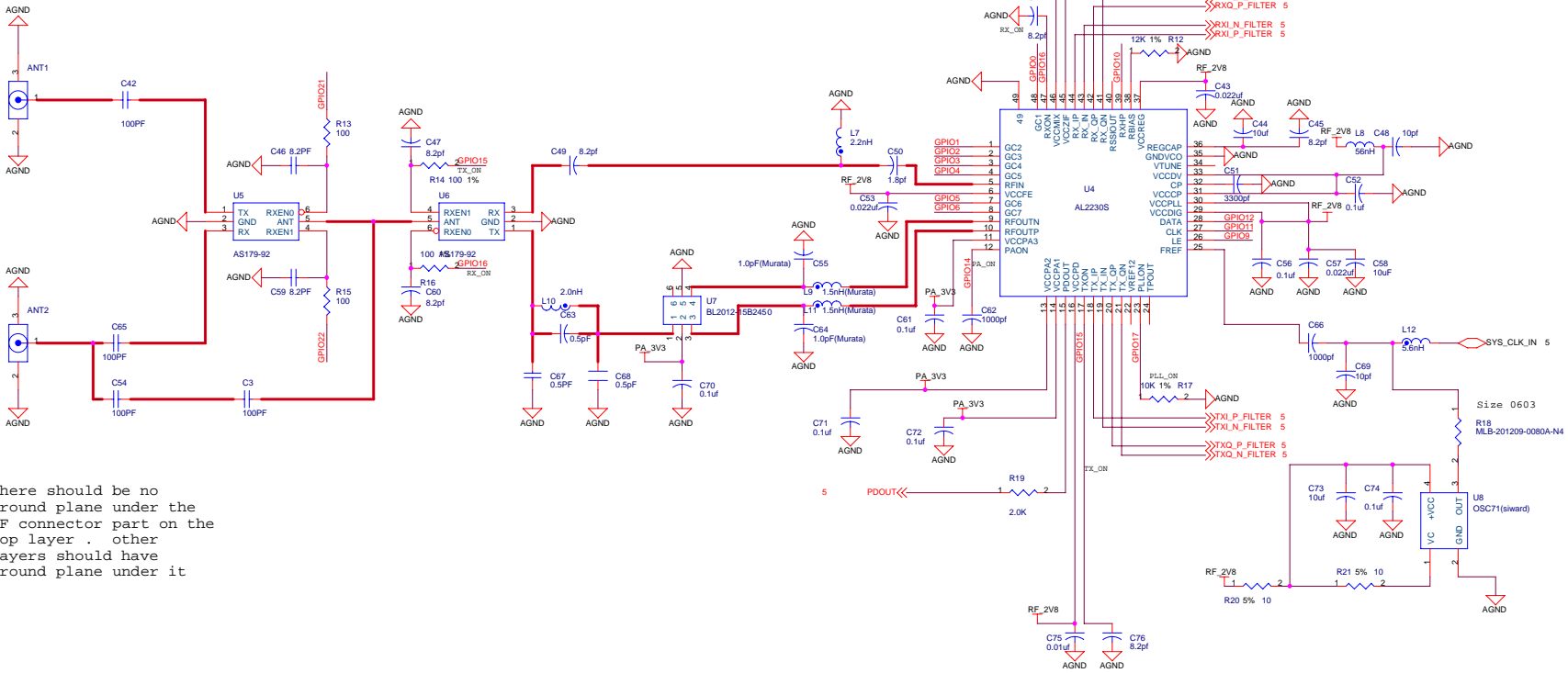
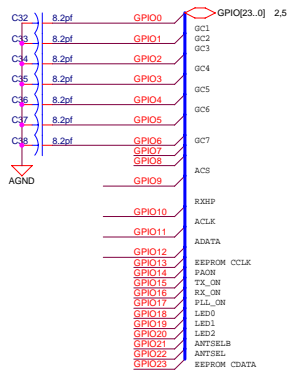
These need to be placed close to power pins



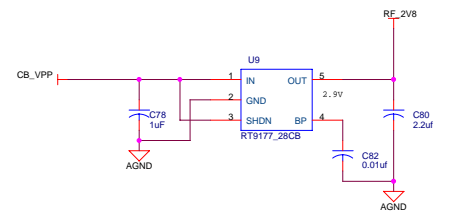
These need to be placed close to power pins



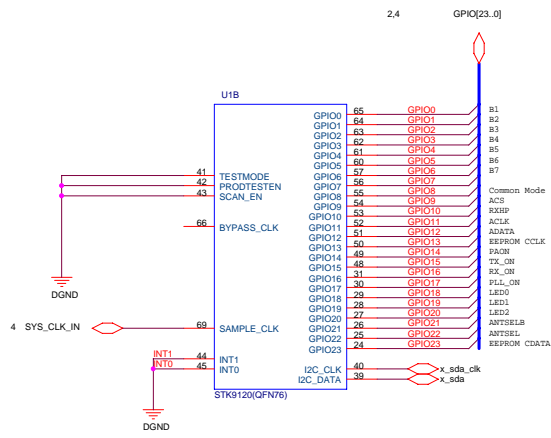
File		
POWER		
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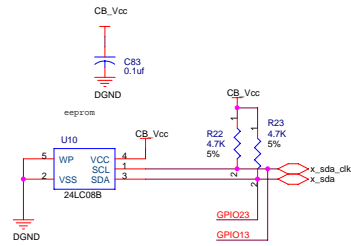
There should be no ground plane under the RF connector part on the top layer. Other layers should have ground plane under it.



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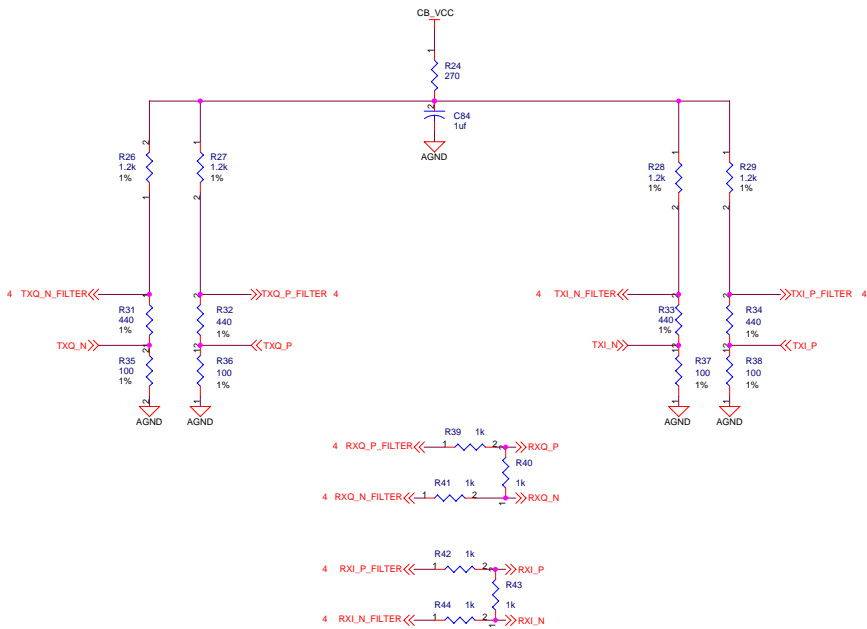


DSP Config and GPIOs

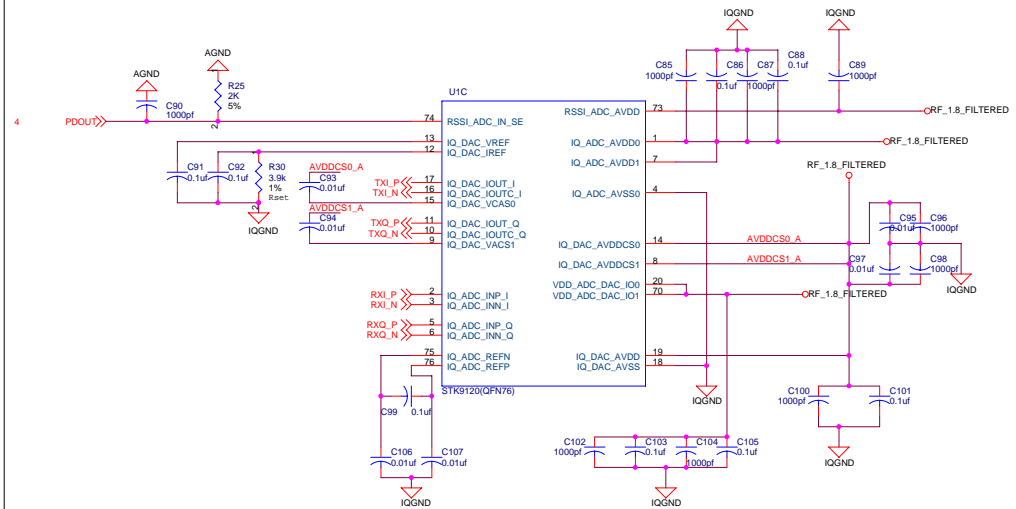


EEPROM

TX/RX RFI



IQ DAC, IQ ADC, RSSI ADC



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